

**AMENDMENTS TO THE SPECIFICATION:**

Please amend the second paragraph on page 33 of the specification as follows:

In Fig. 5, image pickup unit 2 is composed of image pickup element 2b such as CMOS (Complementary Metal Oxide Semiconductor) type image sensor. A bottom surface of rectangular sheet-shaped image pickup element 2b is stuck on the upper surface of base board PC. At the center of the upper surface of the image pickup element 2b, there is formed a photoelectrically-converting section 2d on which pixels are arranged two-dimensionally, and peripheral surface 2a wherein an image processing circuit is structured in image pickup element 2b and inside thereof is formed around the photoelectrically-converting section. In the vicinity of an outer edge of the peripheral surface 2a that crosses a thin side surface ~~face~~ at right angles, there are arranged many pads 2c. The pad 2c representing a terminal for wiring is connected to base board PC through wire W as shown in Fig. 1. The wire W is connected to a prescribed circuit on the base board PC. Thus, image pickup element 2b includes a plate (see, e.g., Figs. 1 and 5) mounted on the base board PC, the photoelectrically converting section 2d provided on a top surface of the plate and having pickup elements (see, e.g., Fig. 5), a peripheral top surface 2a formed on the top surface of the plate around the photoelectrically converting section 2d (see, Fig. 5), and a side surface of the plate adjoining the peripheral top surface 2a (see, Fig. 1).